INTEGRATED CIRCUITS

DATA SHEET

74ABT648

Octal transceiver/register, inverting (3-State)

Product specification
Supersedes data of 1995 Apr 17
IC23 Data Handbook





Octal bus transceiver/register, inverting (3-State)

74ABT648

FEATURES

- Combines 74ABT245 and 74ABT374 type functions in one device
- Independent registers for A and B buses
- Multiplexed real-time and stored data
- Output capability: +64mA/-32mA
- Power-up 3-state
- Power-up reset
- Live insertion/extraction permitted
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model

DESCRIPTION

The 74ABT648 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT648 transceiver/register consists of bus transceiver circuits with inverting 3-State outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or the internal registers. Data on the A or B bus will be clocked into the registers as the appropriate clock pin goes High. Output Enable (OE) and DIR pins are provided to control the transceiver function. In the transceiver mode, data present at the high impedance port may be stored in either the A or B register or both.

The Select (SAB, SBA) pins determine whether data is stored or transferred through the device in real–time. The DIR determines which bus will receive data when the $\overline{\text{OE}}$ is active (Low). In the isolation mode ($\overline{\text{OE}}$ = High), data from Bus A may be stored in the B register and/or data from Bus B may be stored in the A register. Outputs from real-time, or stored registers will be inverted. When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B may be driven at a time. The examples on the next page demonstrate the four fundamental bus management functions that can be performed with the 74ABT648.

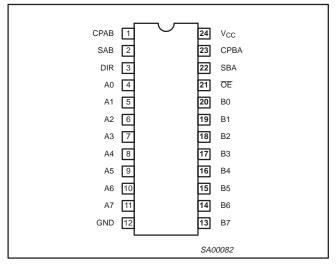
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay An to Bn or Bn to An	$C_L = 50pF; V_{CC} = 5V$	5.9	ns
C _{IN}	Input capacitance CP, S, OE, DIR	V _I = 0V or V _{CC}	4	pF
C _{I/O}	I/O capacitance	Outputs disabled; V _O = 0V or V _{CC}	7	pF
I _{CCZ}	Total supply current	Outputs disabled; V _{CC} =5.5V	110	μΑ

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
24-Pin Plastic DIP	-40°C to +85°C	74ABT648 N	74ABT648 N	SOT222-1
24-Pin plastic SO	-40°C to +85°C	74ABT648 D	74ABT648 D	SOT137-1
24-Pin Plastic SSOP Type II	-40°C to +85°C	74ABT648 DB	74ABT648 DB	SOT340-1
24-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT648 PW	74ABT648PW DH	SOT355-1

PIN CONFIGURATION



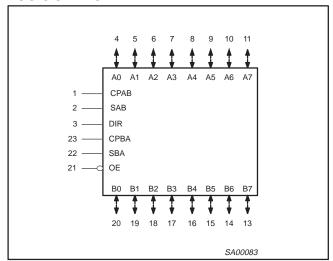
PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1, 23	CPAB / CPBA	A to B clock input / B to A clock input
2, 22	SAB / SBA	A to B select input / B to A select input
3	DIR	Direction control input
4, 5, 6, 7, 8, 9, 10, 11	A0 – A7	Data inputs/outputs (A side)
20, 19, 18, 17, 16, 15, 14, 13	B0 – B7	Data inputs/outputs (B side)
21	ŌĒ	Output enable input (active-Low)
12	GND	Ground (0V)
24	V _{CC}	Positive supply voltage

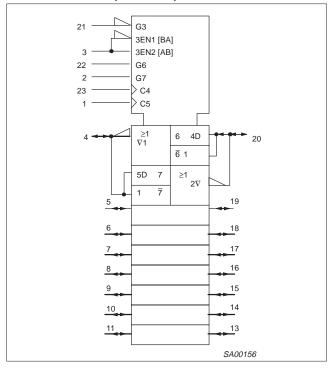
Octal bus transceiver/register, inverting (3-State)

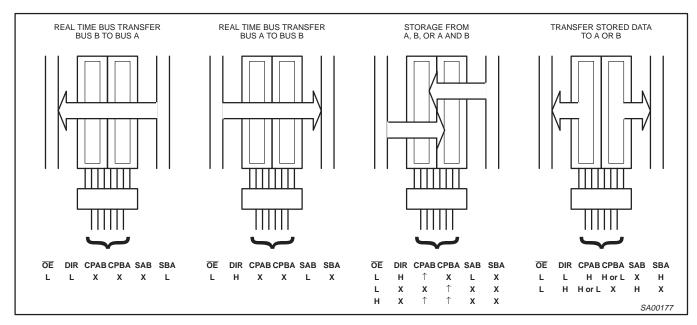
74ABT648

LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)





74ABT648

FUNCTION TABLE

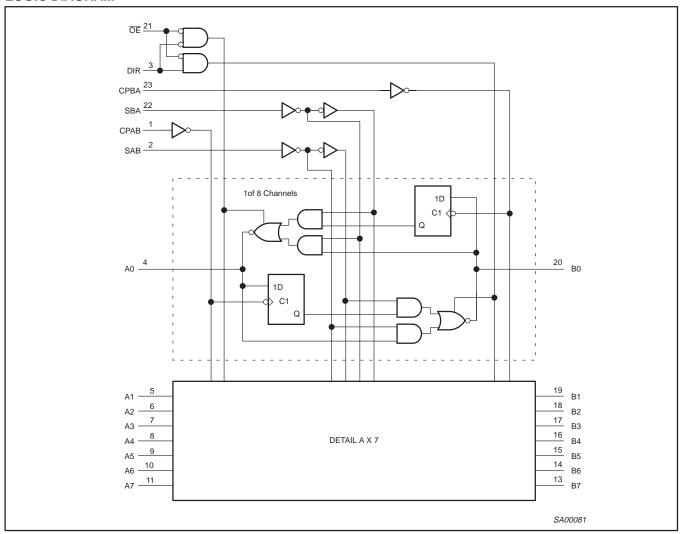
		INPUTS	3			DATA	A I/O	OPERATING MODE
ŌĒ	DIR	CPAB	СРВА	SAB	SBA	An Bn		
Х	Х	↑	Х	Х	Х	Input	Unspecified output*	Store A, B unspecified
Х	Х	Х	\uparrow	Х	Χ	Unspecified output*	Input	Store B, A unspecified
H H	X X	↑ H or L	↑ H or L	X X	X X	Input	Input	Store A and B data Isolation, hold storage
L L	L L	X X	X H or L	X X	L H	Output	Input	Real time \overline{B} data to A bus Stored \overline{B} data to A bus
L L	H H	X H or L	X X	L H	X X	Input	Output	Real time \overline{A} data to B bus Stored \overline{A} data to B bus

H = High voltage level
L = Low voltage level

Don't care

Low-to-High clock transition
The data output function may be enabled or disabled by various signals at the OE input. Data input functions are always enabled, i.e., data at the bus pins will be stored on every Low-to-High transition of the clock.

LOGIC DIAGRAM



Octal bus transceiver/register, inverting (3-State)

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ABSOLUTE MAXIMUM RATINGS1, 2

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
I _{OUT}	DC output current	output in Low state	128	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	ITS	UNIT
		Min	Max	
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{OH}	High-level output current		-32	mA
I _{OL}	Low-level output current		64	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

^{3.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

						LIMITS			
SYMBOL	PARAM	METER	TEST CONDITIONS	Tai	_{mb} = +25	°C	T _{amb} =	–40°C 35°C	UNIT
				Min	Тур	Max	Min	Max	
V _{IK}	Input clamp vo	ltage	$V_{CC} = 4.5V; I_{IK} = -18mA$		-0.9	-1.2		-1.2	V
			$V_{CC} = 4.5V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or V_{IH}	2.5	3.2		2.5		V
V _{OH}	High-level outp	out voltage	$V_{CC} = 5.0V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or V_{IH}	3.0	3.7		3.0		V
			$V_{CC} = 4.5V$; $I_{OH} = -32mA$; $V_I = V_{IL}$ or V_{IH}	2.0	2.3		2.0		V
V _{RST}	Power-up outp voltage ³	ut low	$V_{CC} = 5.5V$; $I_O = 1mA$; $V_I = GND$ or V_{CC}		0.13	0.55		0.55	V
V _{OL}	Low-level output voltage		$V_{CC} = 4.5V$; $I_{OL} = 64mA$; $V_I = V_{IL}$ or V_{IH}		0.42	0.55		0.55	V
l _{OFF}	Power-off leakage current		$V_{CC} = 0.0V$; V_I or $V_O \le 4.5V$		±5.0	±100		±100	μΑ
I _{PU/} I _{PD}	Power–up/down 3-State output current ⁴		V_{CC} = 2.1V; V_{O} = 0.5V; V_{I} = GND or V_{CC} ; V_{OE} = Don't care		±5.0	±50		±50	μА
II	Input leakage	Control pins	$V_{CC} = 5.5V; V_I = GND \text{ or } 5.5V$		±0.01	±1.0		±1.0	μΑ
	current	Data pins	$V_{CC} = 5.5V; V_I = GND \text{ or } 5.5V$		±5	±100		±100	μΑ
I _{IH} + I _{OZH}	3-State output	High current	$V_{CC} = 5.5V; V_O = 2.7V; V_I = V_{IL} \text{ or } V_{IH}$		5.0	50		50	μΑ
I _{IL} + I _{OZL}	3-State output	Low current	$V_{CC} = 5.5V; V_{O} = 0.5V; V_{I} = V_{IL} \text{ or } V_{IH}$		-5.0	-50		-50	μΑ
ICEX	Output high lea	akage current	$V_{CC} = 5.5V; V_{O} = 5.5 V; V_{I} = GND \text{ or } V_{CC}$		5.0	50		50	μΑ
I _O	Output current	1	$V_{CC} = 5.5V; V_{O} = 2.5V$	-50	-65	-180	-50	-180	mA
I _{CCH}			$V_{CC} = 5.5V$; Outputs High, $V_I = GND$ or V_{CC}		110	250		250	μΑ
I _{CCL}	Quiescent sup	ply current	V_{CC} = 5.5V; Outputs Low, V_I = GND or V_{CC}		20	30		30	mA
I _{CCZ}			V_{CC} = 5.5V; Outputs 3-State; V_{I} = GND or V_{CC}		110	250		250	μА
Δl _{CC}	Additional supplinput pin ²	oly current per	V_{CC} = 5.5V; one input at 3.4V, other inputs at V_{CC} or GND; V_{CC} = 5.5V		0.3	1.5		1.5	mA

NOTES:

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
 This is the increase in supply current for each input at 3.4V.
 For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.
 This parameter is valid for any V_{CC} between 0V and 2.1V, with a transition time of up to 10msec. From V_{CC} = 2.1 to V_{CC} = 5V ± 10% a transition time of up to 100µsec is permitted.

Octal bus transceiver/register, inverting (3-State)

74ABT648

AC CHARACTERISTICS

GND = 0V, t_R = t_F = 2.5ns, C_L = 50pF, R_L = 500 Ω

					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	1	Γ _{amb} = +25° V _{CC} = +5.0\	C /	+8	= -40 to 5°C .0V ±0.5V	UNIT
			Min	Тур	Max	Min	Max	
f _{MAX}	Maximum clock frequency	1	125	200		125		MHz
t _{PLH} t _{PHL}	Propagation delay CPAB to Bn or CPBA to An	1	2.2 1.7	5.3 5.9	6.8 7.4	2.2 1.7	7.8 8.4	ns
t _{PLH}	Propagation delay	2	1.0	3.6	5.1	1.0	6.1	ns
t _{PHL}	An to Bn or Bn to An	3	1.5	4.2	5.6	1.5	6.3	
t _{PLH}	Propagation delay	2	1.5	4.9	6.1	1.5	7.1	ns
t _{PHL}	SAB to Bn or SBA to An	3	1.5	5.4	6.9	1.5	7.7	
t _{PZH}	Output enable time	5	1.0	4.3	5.3	1.0	6.3	ns
t _{PZL}	OE to An or Bn	6	2.1	5.5	7.4	2.1	8.8	
t _{PHZ}	Output disable time	5	1.5	6.2	7.3	1.5	8.3	ns
t _{PLZ}	OE to An or Bn	6	1.5	6.0	7.0	1.5	7.5	
t _{PZH}	Output enable time	5	1.2	4.8	5.7	1.2	6.7	ns
t _{PZL}	DIR to An or Bn	6	2.5	6.0	9.0	2.5	9.5	
t _{PHZ}	Output disable time	5	1.5	5.9	6.7	1.5	7.7	ns
t _{PLZ}	DIR to An or Bn	6	1.5	6.3	7.2	1.5	8.2	

AC SETUP REQUIREMENTS

 $\mbox{GND} = \mbox{OV}, \, t_R = t_F = 2.5 \mbox{ns}, \, C_L = 50 \mbox{pF}, \, R_L = 500 \Omega$

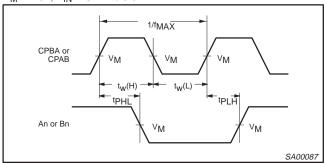
				LIN	IITS	
SYMBOL	PARAMETER	WAVEFORM	T _{amb} = V _{CC} =	: +25°C : +5.0V	T_{amb} = -40 to +85°C V_{CC} = +5.0V \pm 0.5V	UNIT
			Min	Тур	Min	
$t_{s}(H)$ $t_{s}(L)$	Setup time An to CPAB, Bn to CPBA	4	3.0 3.0	1.5 1.0	3.0 3.0	ns
t _h (H) t _h (L)	Hold time An to CPAB, Bn to CPBA	4	0.0 0.0	-0.4 -1.0	0.0 0.0	ns
t _w (H) t _w (L)	Pulse width, High or Low CPAB or CPBA	1	3.5 4.0	2.6 1.0	3.5 4.0	ns

Octal bus transceiver/register, inverting (3-State)

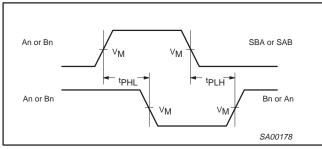
74ABT648

AC WAVEFORMS

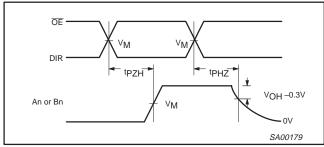
 $V_M = 1.5V$, $V_{IN} = GND$ to 3.0V



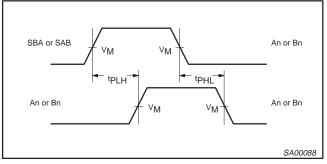
Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



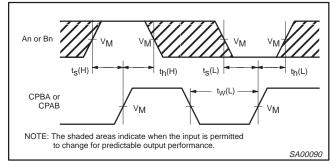
Waveform 3. Propagation Delay, An to Bn or Bn to An and SBA to An or SAB to Bn



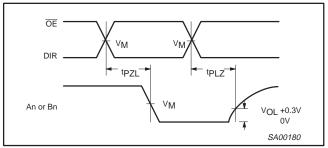
Waveform 5. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 2. Propagation Delay, SAB to Bn or SBA to An



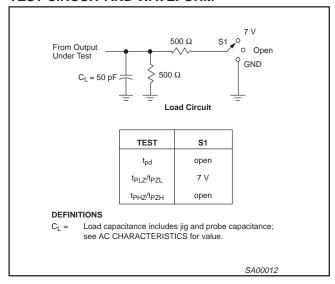
Waveform 4. Data Setup and Hold Times



Waveform 6. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

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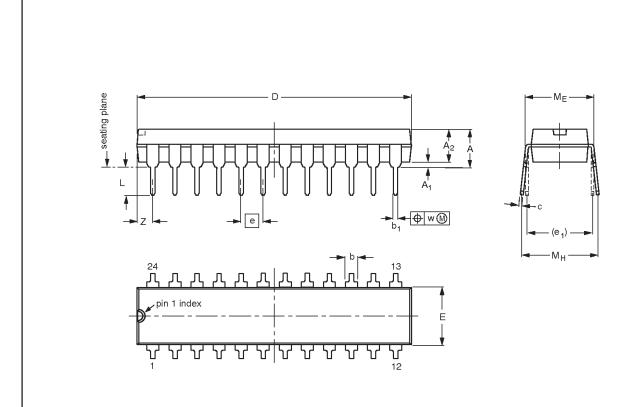
TEST CIRCUIT AND WAVEFORM

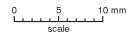


74ABT648

DIP24: plastic dual in-line package; 24 leads (300 mil)

SOT222-1





DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.70	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.48	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.255	0.100	0.300	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

Note

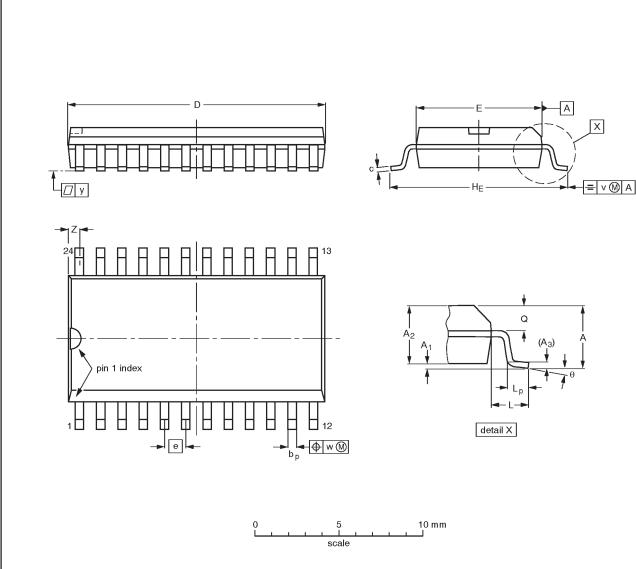
1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT222-1		MS-001AF			95-03-11

74ABT648

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

	•						_			•								
UNIT	A max.	A ₁	A ₂	А3	bр	c	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Ø	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

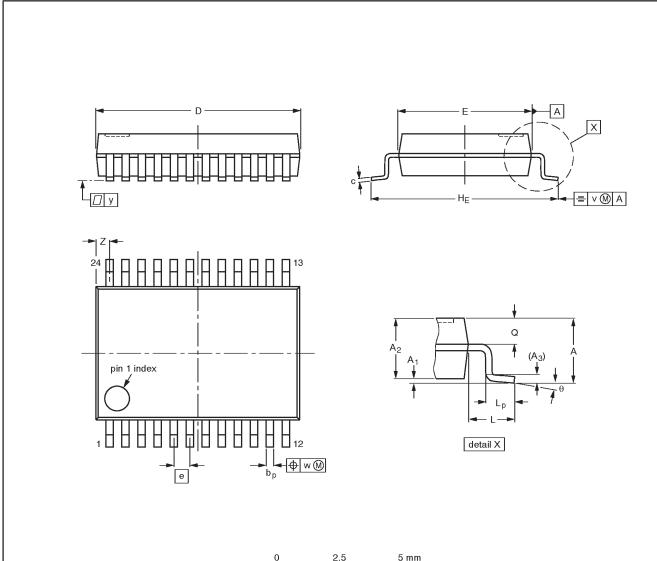
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT137-1	075E05	MS-013AD				-92-11-17 95-01-24

74ABT648

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



0 2.5 5 mm

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	рb	O	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Œ	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

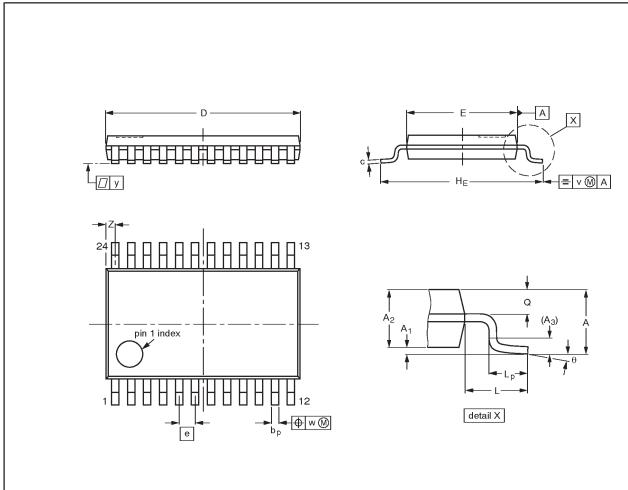
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT340-1		MO-150AG				93-09-08 95-02-04

Octal bus transceiver/register, inverting (3-State)

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TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	c	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT355-1		MO-153AD				93-06-16 95-02-04

Octal transceiver/register, inverting (3-State)

74ABT648

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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